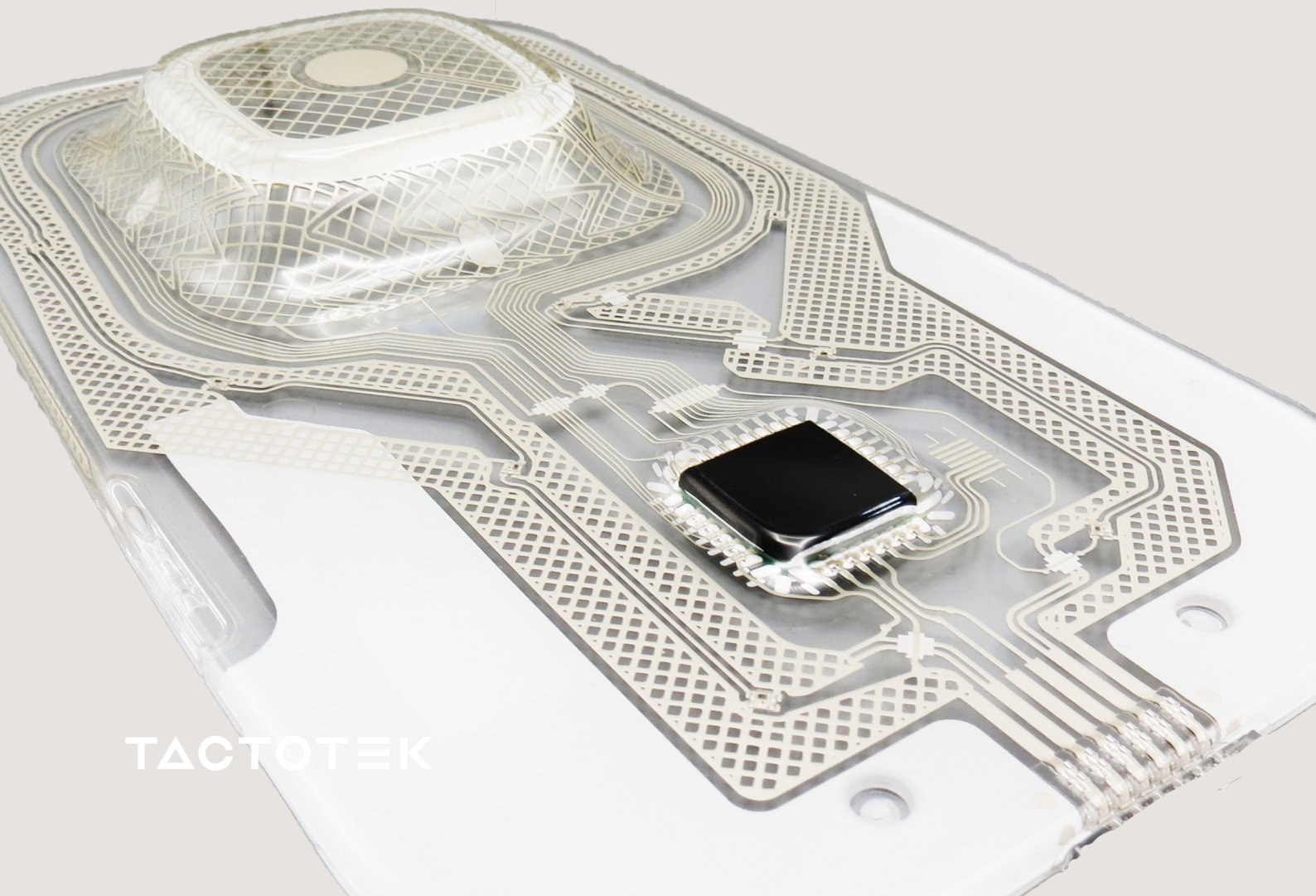
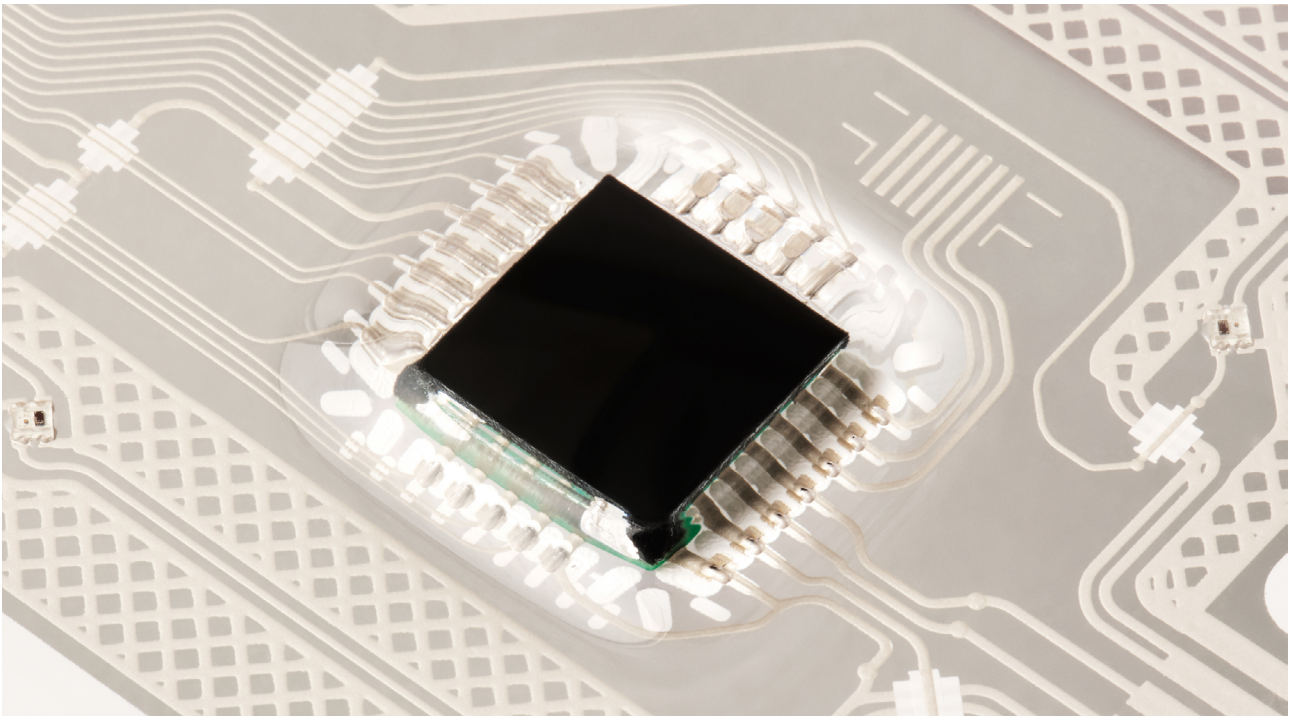


# Adding In Mold Intelligence to Smart Surfaces with IMSE<sup>®</sup> System in Package Electronics

TactoTek<sup>®</sup> IMSE<sup>®</sup> SiP



TACTOTEK



IMSE® SiP

## IMSE® SiP – System in Package

With IMSE® SiP your IMSE part becomes truly digital, adding functionality, efficiency and higher integration all in one package.

By embedding all electronics inside 3D injection molded plastics, IMSE SiP enables a new level of electrical and mechanical integration and eliminates the need for external control electronics.

Increasing the integration level and functionality does not mean increased system level complexity: IMSE SiP simplifies wiring and significantly reduces the number of interfaces between the host system and the IMSE part.

Standalone digital parts enable easy customization by software.

### IMSE SiP Overview

- Designed specifically for in mold applications
- Surface mount using standard high speed SMT equipment
- IMSE specific landing pattern for electrical connections
- 15mm by 15mm with 24 pads size to fit any design
- Different sizes and denser pitch versions under development

Start building smarter  
surfaces today with the  
help of TactoTek®

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